## ne<mark>x</mark>peria

## **Quarterly Reliability Monitoring Results**

Quarters: Q1/2022 to Q4/2023

Based on structural similarity

Supplier		User Part Number						
Nexperia B.V.		PMEG45T10EXD						
Name of Laboratory Assembly reliability labs Test		Part Description						
		Nexperia DHAM	Schottky					
		SMD package						
		Test Conditions Duration # Lots # Quantity # Reje						
	TEST							
	Pre- and Post-Stress							
# 1	Electrical Test	Tamb = 25 °C	N/A	see below	all parts	see below		
		JESD22-A113						
		Bake Tamb = 125 °C	24 hours					
	PC	Soak Tamb = 85 °C, RH = 85%	168 hours					
# 2	Preconditioning	Reflow soldering	3 cycles	1514	64430	0		
		MIL-STD-750-1						
	HTRB	M1038 Method A Tj = Tjmax, Vr = 100% of max. datasheet						
# F	High Temperature Reverse Bias	reverse voltage <sup>[1]</sup>	1000 haure	206	0220	0		
# 5	5003		1000 hours	206	9320	0		
	тс	JESD22-A104						
# 7	Temperature Cycling	-65 °C to Tjmax, not to exceed 150°C	500 cycles	311	14080	0		
# /	· · · · · · · · · · · · · · · · · · ·		500 cycles	511	14000	0		
	UHAST	JESD22-A118						
# 8 <b>or</b>	Unbiased HAST	Tamb = 130 °C, RH = 85 %	96 hours	311	14080	0		
		JESD22-A102						
	AC	Tamb = 121 °C, RH = 100 %						
# 8a	Autoclave	Pressure = 205 kPa (29.7 psia)						
	H3TRB	JESD22-A101						
	High Humidity High	Tamb = 85 °C, RH = $85\%$ , VR = 80 % of						
# 9	Temperature Reverse Bias	rated reverse voltage <sup>[1], [2]</sup>	1000 hours	311	14080	0		
		MIL-STD-750 Method 1037						
	IOL	ton = toff, devices powered to insure $\Delta T j$ =						
# 10	Intermittent Operating Life	100 °C	333 hours	312	14120	0		
	BCH							
# 20	<b>RSH</b> Resistance to Solder Heat	JESD22-A111	10 -	260	0070	0		
# 20	SD	200 C ± 5 C	10 s	269	8070	0		
# 21	SD Solderability	J-STD-002		222	6660	0		
	,	dos have to be considered (thermal runaway)		222	6660	U		

[1] The physical limitations of Schottky diodes have to be considered (thermal runaway).

[2] The maximum applied voltage is limited by test chamber set up and does not exceed 115V.

## **Calculation of FIT and MTTF**

Test considered for FIT calculation: High Temperature Reverse Bias (HTRB, Test # 5) Confidence level 60%, derated to 55 °C, activation energy 0.7 eV, test time 168 to 1000 hours

Wafer Fab 1	Technology	Quantity	Rejects	Failure Rate (FIT)	MTTF (hrs)
Nexperia					
DHAM S	Schottky	9320	0	0,46	2,19E+09

© 2024 Nexperia B.V.

All information hereunder is per Nexperia's best knowledge. This document does not provide for any representation or warranty express or implied by Nexperia. In case Nexperia has tested the product, this documentation reflects the outcome of the analysis of the actually tested parts only.

nexperia.com